

IN THE CLAIMS:

A rewritten version of the entire set of pending claims is as follows:

26. (Amended) An apparatus comprising:

a housing;

an opening in the housing configured to pass a substrate into the housing;

a chuck located within the housing, wherein the chuck is configured to hold the substrate for processing and wherein the substrate may be spun using the chuck;

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an inlet within the housing, wherein the inlet is configured for connection to a source for a precursor silica solution and wherein the inlet is configured to deposit the precursor silica solution onto the substrate held by the chuck and wherein a film of the precursor solution may be formed on the substrate; and

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a filter unit, wherein the filter unit is configured to receive a catalyst and introduce the catalyst onto the wafer in a uniform manner such that the catalyst becomes homogeneously diffused into the film, wherein the filter unit includes a dispense head that dispenses the catalyst and a vapor distribution unit that uniformly distributes the catalyst.

27. (Unchanged) The apparatus of claim 26, wherein the substrate is a semiconductor wafer.

28. (Unchanged) The apparatus of claim 26, wherein the substrate is a substrate for an integrated circuit.

29. (Unchanged) The apparatus of claim 26, wherein the substrate is a substrate for a chemical sensor.

30. (New) The apparatus of claim 26, wherein the vapor distribution unit is a mesh unit.

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31. (New) The apparatus of claim 30, wherein the mesh unit is made of a polytetrafluoroethylene material.